PCS Band

PCS Band RF Linear LDMOS Amplifier

Designed for ultra-linear amplifier applications in 50 ohm systems operating in the PCS frequency band. A silicon FET Class A design provides outstanding linearity and gain. In addition, the excellent group delay and phase linearity characteristics are ideal for digital modulation systems, such as TDMA and CDMA.

Replaced by MHL19936N. There are no form, fit or function changes with this part replacement. N suffix added to part number to indicate transition to lead-free

- Third Order Intercept: 49.5 dBm Typ
- Power Gain: 29 dB Typ (@ f = 1960 MHz)
- · Excellent Phase Linearity and Group Delay Characteristics
- Ideal for Feedforward Base Station Applications

MHL19936

1900-2000 MHz 12 W, 29 dB RF LINEAR LDMOS AMPLIFIER

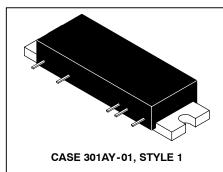


Table 1. Absolute Maximum Ratings (T_C = 25°C unless otherwise noted)

Rating	Symbol	Value	Unit
DC Supply Voltage	V_{DD}	30	Vdc
RF Input Power	P _{in}	+16	dBm
Storage Temperature Range	T _{stg}	- 40 to +100	°C
Operating Case Temperature Range	T _C	- 20 to +100	°C

Table 2. Electrical Characteristics (V_{DD} = 26 Vdc, T_{C} = 25°C; 50 Ω System)

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Characteristic		Symbol	Min	Тур	Max	Unit
Supply Current		I _{DD}	_	1.4	1.45	Α
Power Gain	(f = 1960 MHz)	G _p	28	29	30	dB
Gain Flatness	(f = 1900 - 2000 MHz)	G _F	_	0.2	0.4	dB
Power Output @ 1 dB Comp.	(f = 1950 MHz)	P1dB	40	41	_	dBm
Input VSWR	(f = 1900 - 2000 MHz)	VSWR _{in}	_	1.2:1	1.5:1	
Third Order Intercept	(f1 = 1950 MHz, f2 = 1955 MHz)	ITO	49	49.5	_	dBm
Noise Figure	(f = 2000 MHz)	NF	_	4.2	4.5	dB





TYPICAL CHARACTERISTICS

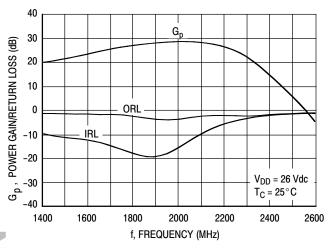


Figure 1. Power Gain, Input Return Loss, Output Return Loss versus Frequency

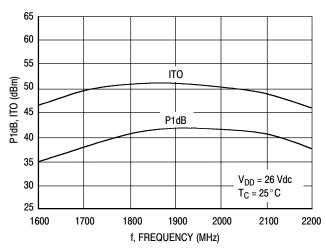


Figure 2. P1dB, ITO versus Frequency

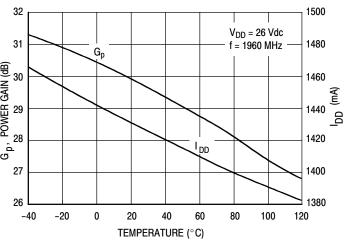


Figure 3. Power Gain, I_{DD} versus Temperature

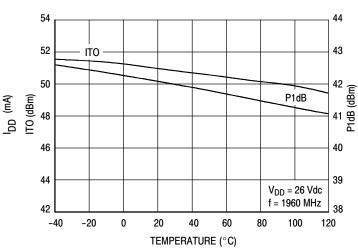


Figure 4. ITO, P1dB versus Temperature

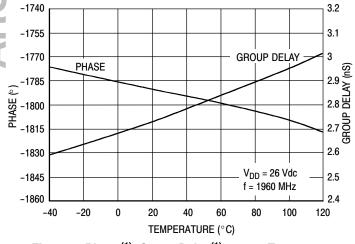


Figure 5. Phase⁽¹⁾, Group Delay⁽¹⁾ versus Temperature

1. In Production Test Fixture

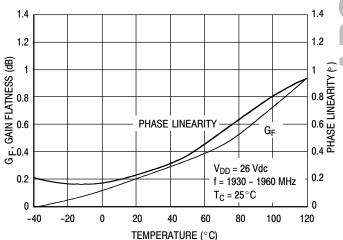
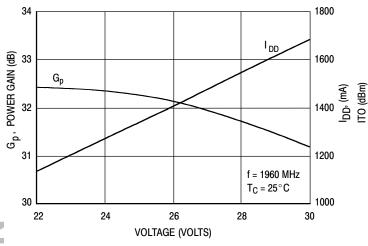


Figure 6. Gain Flatness, Phase Linearity versus Temperature



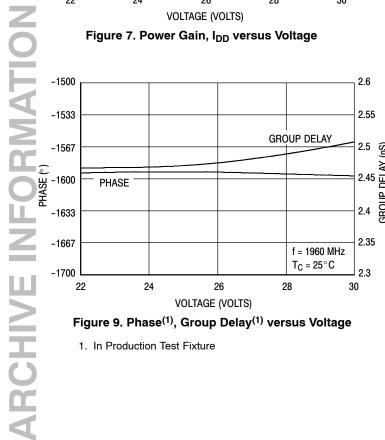
TYPICAL CHARACTERISTICS



53 44 P1dB f = 1960 MHz 52 43 $T_C = 25^{\circ}C$ 42 51 P1dB (dBm) 50 ITO f1 = 1957 MHz f2 = 1962 MHz 40 49 $T_C = 25^{\circ}C$ 39 48 38 47 30 22 24 26 28 **VOLTAGE (VOLTS)**

Figure 7. Power Gain, I_{DD} versus Voltage

Figure 8. ITO, P1dB versus Voltage



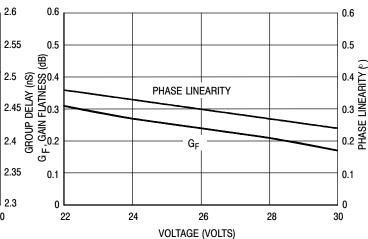


Figure 9. Phase⁽¹⁾, Group Delay⁽¹⁾ versus Voltage

1. In Production Test Fixture

Figure 10. Phase Linearity, Gain Flatness versus Voltage



NOTES





NOTES

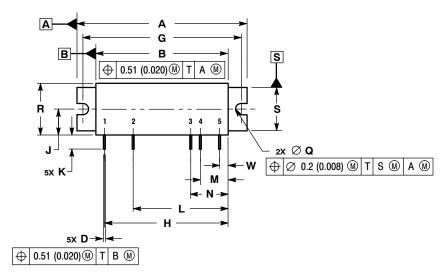


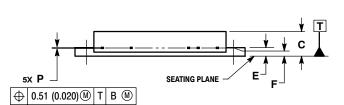
NOTES



ARCHIVE INFORMATION

PACKAGE DIMENSIONS





CASE 301AY-01 ISSUE 0

- NOTES:
 1. CONTROLLING DIMENSION: MILLIMETER.
 2. INTERPRET DIMENSIONS AND TOLERANCES PER ANSI Y14.5M, 1982.
 3. DIMENSION F TO CENTER LINE OF LEADS.

	MILLIN	IETERS	INCHES			
DIM	MIN	MAX	MIN	MAX		
Α	44.7	45.21	1.760	1.780		
В	34.8	35.31	1.370	1.390		
C	6.22	6.73	0.245	0.265		
D	0.43	0.58	0.017	0.023		
E	2.03	2.54	0.080	0.100		
F	2.18	BSC	0.086 BSC			
G	41.91	BSC	1.650 BSC			
Н	32.77 BSC		1.290 BSC			
J	6.76	7.11	0.266	0.280		
K	3.18	4.19	0.125	0.165		
L	25.15	BSC	0.990 BSC			
M	7.37 BSC		0.290 BSC			
N	9.91	9.91 BSC		0.390 BSC		
P	0.2	0.33	0.008	0.013		
Q	3	3.35	0.118	0.132		
R	13.59	14.1	0.535	0.555		
S	11.3	11.81	0.445	0.465		
W	2.29	BSC	0.090 BSC			

STYLE 1: PIN 1. RF INPUT 2. VDD1

3. VDD2 4. VDD3 5. RF OUTPUT CASE: GROUND

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